Supplier Name: Contact Info: Form/Declaration Type: Created on:

Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support Distribute - RoHS and IEC 62474 DB

08/25/2022

Details for "TL062IPWR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TL062IPWR	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	PW 8	4.4x3x1.15	34.4

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level			
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm		
Bond Wire									
Precious Metals	Gold	7440-57-5	0.038415	100	1000000	0.111616	1116		
Sub-Total			0.038415	100	1000000	0.111616	1116		
Die Attach Adhesive									
Precious Metals	Silver	7440-22-4	0.323535	79.999951	800000	0.940039	9400		
Thermoplastics	Ероху	85954-11-6	0.080884	20.000049	200000	0.23501	2350		
Sub-Total			0.404419	100	1000000	1.17505	11750		
Lead Frame									
Copper and Its Alloys	Copper	7440-50-8	12.6633	97.41	974100	36.793537	367935		
Copper and Its Alloys	Iron	7439-89-6	0.312	2.4	24000	0.906524	9065		
Copper and Its Alloys	Phosphorus	7723-14-0	0.0039	0.03	300	0.011332	113		
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.0039	0.03	300	0.011332	113		
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.0039	0.03	300	0.011332	113		
Zinc and Its Alloys	Zinc	7440-66-6	0.013	0.1	1000	0.037772	378		
Sub-Total			13	100	1000000	37.771827	377718		
Lead Frame Plating									
Nickel and Its Alloys	Nickel	7440-02-0	0.247312	95.12	951200	0.718571	7186		
Precious Metals	Gold	7440-57-5	0.002028	0.78	7800	0.005892	59		
Precious Metals	Palladium	7440-05-3	0.01066	4.1	41000	0.030973	310		
Sub-Total			0.26	100	1000000	0.755437	7554		
Mold Compound									
Other Inorganic Materials	Fused Silica	60676-86-0	16.676043	86.000003	860000	48.452663	484527		
Other Plastics and Rubber	Carbon Black	1333-86-4	0.058172	0.299999	3000	0.16902	1690		
Thermoplastics	Epoxy	85954-11-6	2.656532	13.699998	137000	7.718621	77186		
Sub-Total			19.390747	100	1000000	56.340303	563403		
Semiconductor Device									
Ceramics / Glass	Doped Silicon	7440-21-3	1.323605	100	1000000	3.845768	38458		
Sub-Total			1.323605	100	1000000	3.845768	38458		
Total			34.417186			100	1000000		

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one Ti part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different Ti part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

Ti bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 08/25/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the ROHS Annex II threshold, but that fall within one of the specific ROHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.